

Application No.: 10/667,605Docket No.: 4459-130

ABSTRACT

An optical semiconductor package ~~comprises~~ includes a substrate, a chip, a plurality of bonding wires, a window, a supporter, and an encapsulant. The chip is disposed on the substrate and has an optical element. The bonding wires are used for electrically connecting the chip to the substrate. The window is supported on the supporter and positioned over the optical element of the chip. The encapsulant is overmolded on the substrate for fixing the window and encapsulating the chip and the bonding wires.

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